LG

LIGHT ELECTRONICS CO., LTD.

Part No.	LGE [illegible]4C-707-T1	Page	1 of 8

Electrical Optical Characteristics at Ta=25℃

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant Intensity	Ie	2.2	3.1	4.5	mW/sr	I_F=20mA (Note 1,3)
Viewing Angle	1/2	---	85	---	deg	(Note 2)
Peak Wavelength		---	940	---	nm	I_F=20mA
Spectral Line Half- Width	Δ	---	50	---	nm	I_F=20mA
Forward Voltage	V_F	---	1.22	1.5	V	I_F=50mA
Reverse Current	I_R	---	---	100	μA	V_R=8V

Note:

1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.

2. -axis angle at which the Radiant Intensity is half the axial Radiant Intensity.

3. The Ie guarantee should be added ±15% tolerance.

Infrared Emitting Diode Specification

●Commodity: Infrared emitting diode

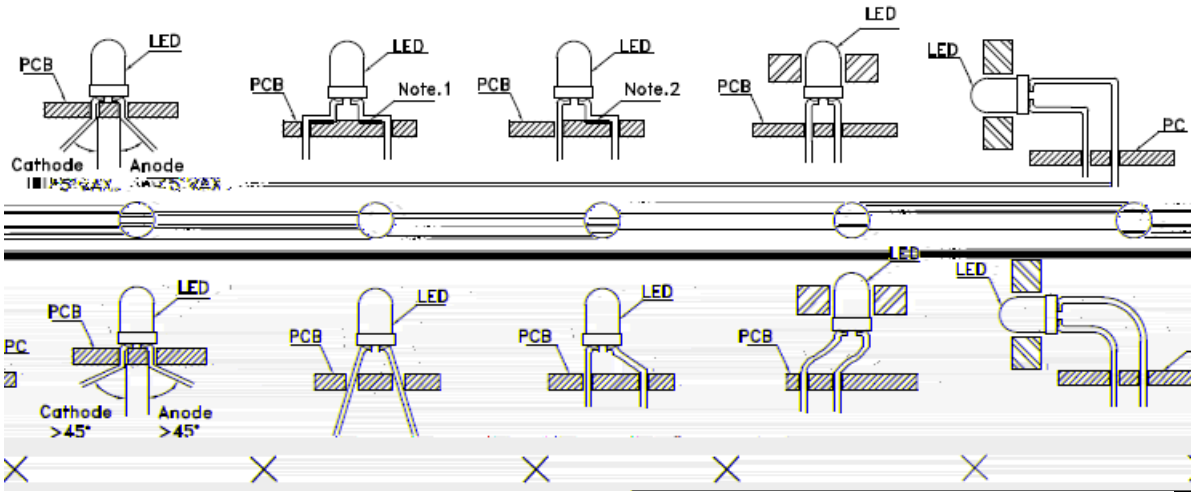
●Intensity Bin Limits (At 20mA)

BIN CODE	Min. (mW/sr)	Max. (mW/sr)
1	2.2	2.6
2	2.6	3.1
3	3.1	3.7
4	3.7	4.5

NOTE: The Ie guarantee should be added ±15% tolerance.

LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.(Fig.1)



-2:Do not route PCB Trace in the contact area between the leadframe and the PCB to prevent short-circuit.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2)

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

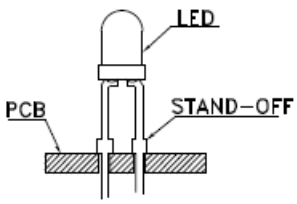


Fig. 3

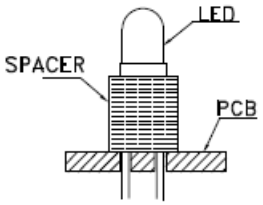


Fig. 4

LEAD FORMING PROCEDURES 0 1 9] T J 1 . B T 1 0 0 1